

Amendment to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended): An integrated circuit (IC) comprising:
 - a primary substrate having a top surface, a bottom surface, and a plurality of side surfaces;
 - a plurality of contacts on the top surface of the primary substrate connectable to pins of a packaging element; and
 - a capacitive coating directly contacting at least the bottom surface of the primary substrate to make contact with a lead frame intended to secure the primary substrate to the packaging element.
2. (Original): The IC of claim 1, wherein the capacitive coating has a capacitance that is lower than an internal capacitance of the IC.
3. (Original): The IC of claim 1, wherein the capacitive coating extends from the bottom surface to the plurality of side surfaces of the primary substrate.
4. (Original): The IC of claim 1, wherein the capacitive coating is a capacitive dielectric.
5. (Original): The IC of claim 4, wherein the capacitive dielectric has a low k value.

6. (Original): The IC of claim 1, wherein the capacitive coating has a thickness of between 0.01 millimeters and 1.0 millimeters.

7. (Original): The IC of claim 1, wherein the capacitive coating has a thickness of substantially 0.1 millimeters.

8. (Currently amended): An electronic device comprising:
a packaging element having a number of pins to externally connect the electronic device;
an integrated circuit (IC) having a top surface, a bottom surface, and a plurality of side surfaces;
a plurality of contacts on the top surface of the IC and connected to the pins of the packaging element;
a capacitive coating directly contacting at least the bottom surface of the IC; and
a lead frame to secure the IC to the packaging element, the capacitive coating sandwiched between the IC and the lead frame.

9. (Original): The electronic device of claim 8, wherein the capacitive coating has a capacitance that is lower than an internal capacitance of the IC.

10. (Original): The electronic device of claim 8, wherein the capacitive coating extends from the bottom surface to the plurality of side surfaces of the IC.

11. (Original): The electronic device of claim 8, wherein the capacitive coating is a capacitive dielectric.

12. (Original): The electronic device of claim 11, wherein the capacitive dielectric has a low k value.

13. (Original): The electronic device of claim 11, wherein the capacitive coating has a thickness of between 0.01 millimeters and 1.0 millimeters.

14. (Original): The electronic device of claim 11, wherein the capacitive coating has a thickness of substantially 0.1 millimeters.

15-20. (Canceled)